

Title (en)

Method for fixing a footwear sole to the footwear upper

Title (de)

Verfahren zum Befestigen einer Schuhsohle an der Schuhoberstruktur

Title (fr)

Procédé de fixation d'une semelle de chaussure à la tige de la chaussure

Publication

**EP 2630883 A1 20130828 (EN)**

Application

**EP 13000594 A 20130206**

Priority

ES 201200208 A 20120221

Abstract (en)

The present invention relates to a method for fixing a footwear sole to the footwear upper. The method of the invention is envisaged for gluing a footwear sole to the footwear upper, without prior or external manipulation of the sole and without applying chlorinated solvents or organic solvents for treating the surfaces of the soles that is performed conventionally. The method involves different steps consisting of receiving the soles, recognizing the soles by means of modeling in three dimensions, followed by another step of determining the thermodynamic variables of the materials making up the sole, this phase being performed by means of thermal parameterization and cleaning of the surfaces, for subsequently treating the sole by means of ultraviolet radiation and applying ozone in combination. The corresponding adhesive is then applied both on the sole and the upper, with subsequent fixing and drying by providing heat energy, a step of removing the solvent from the adhesive both in the sole and in the upper then being performed, and finally the adhesive both of the surface of the upper and of the surface of the sole are adapted so that they contact one another and gluing or attaching the sole and the upper by means of suitable pressure.

IPC 8 full level

**A43B 9/12** (2006.01); **A43D 1/08** (2006.01); **A43D 25/20** (2006.01)

CPC (source: EP ES)

**A43B 9/12** (2013.01 - EP); **A43D 1/08** (2013.01 - EP); **A43D 25/06** (2013.01 - ES); **A43D 25/18** (2013.01 - ES); **A43D 25/20** (2013.01 - EP)

Citation (search report)

- [A] WO 2008122874 A1 20081016 - ALC FLENCO S R L [IT], et al
- [A] EP 1234517 A1 20020828 - VIATECNIA SL [ES]
- [A] US 2010040889 A1 20100218 - HARANO KENICHI [JP], et al

Cited by

CN105266279A; CN104146441A; WO2015139323A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 2630883 A1 20130828**; ES 2420762 A1 20130826; ES 2420762 B1 20140617

DOCDB simple family (application)

**EP 13000594 A 20130206**; ES 201200208 A 20120221